1-2102061-6 V ACTIVE

Mezalok | AMP Mezalok

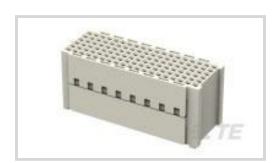
TE Internal #: 1-2102061-6

AMP Mezalok, PCB Mount Receptacle, Vertical, Board-to-Board, 114 Position, 1.27mm [.05in] Centerline, Gold, Printed Circuit Board

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Connectors > PCB Connectors > Board-to-Board Connectors > Board-to-Board Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 114

Centerline (Pitch): 1.27 mm [.05 in]

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Receptacle
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Rows	6
Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	114
Board-to-Board Configuration	Parallel

Electrical Characteristics

Dielectric Withstanding Voltage (Max)	750 VAC
Operating Voltage	250 VAC

Contact Features

Contact Layout	Matrix
Mating Tab Width	.43 mm[.017 in]
Mating Tab Thickness	.46 mm[.018 in]
Contact Shape & Form	Square
Contact Mating Area Plating Material Finish	Bright



Termination Method to Printed Circuit Board Mechanical Attachment PCB Mount Alignment Type PCB Mount Retention Type Noting Alignment Mating Alignment Mating Alignment Type PCB Mount Retention Mithout Mating Alignment Without PCB Mount Alignment Without PCB Mount Alignment Without Connector Mounting Type Board Mount Connector Mounting Type Mating Entry Location Centerline (Pitch) 1.27 mm[.05 in] Housing Color Natural Housing Material Connector Height Row-to-Row Spacing Stack Height PCB Thickness (Recommended) Userating Temperature Range Surface Mount - Solder Ball Without None None None None None None None None Natural LCP (Liquid Crystal Polymer) Stack Height None, 127 mm[.05 in] Stack Height None, 128 mm[.091 in] Sasge Conditions Operating Temperature Range		
Contact Mating Area Plating Material Contact Mating Area Plating Material Thickness Contact Mating Area Plating Material Thickness Contact Type Socket Contact Type Socket Contact Current Rating (Max) 1.5 A Termination Features Termination Method to Printed Circuit Board Mechanical Attachment PCB Mount Alignment Type None PCB Mount Alignment Type Solder Ball Mating Alignment Mating Alignment Type Polarizing Tab Polarizing Tab PCB Mount Alignment Type Without Connector Mounting Type Board Mount Connector Mounting Type Board Mount Connector Mounting Type Board Mount Contertine (Pitch) 1.27 mm[05 in] Housing Color Rousing Material Connector Height Row-to-Row Spacing 1.27 mm[05 in] Stack Height PCB Thickness (Recommended) Sage Conditions Operating Temperature Range Departion/Application Pick and Place Cover	Contact Underplating Material	Nickel
Contact Mating Area Plating Material Thickness 7.6 μm [29.9212 μin] Contact Type Socket Contact Current Rating (Max) 1.5 A Fermination Features Termination Method to Printed Circuit Board Surface Mount - Solder Ball Methanical Attachment PCB Mount Alignment Type None PCB Mount Retention Type Solder Ball Mithing Alignment Type Polarizing Tab Mating Alignment Type Polarizing Tab PCB Mount Retention Without Connector Mounting Type Board Mount Connector Mounting Type Connector Mo	Contact Base Material	Beryllium Copper
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Connector Height 11 mm[.432 in] Row-to-Row Spacing 1.27 mm[.05 in] Stack Height 15 mm[.591 in] PCB Thickness (Recommended) 2.36 mm[.093 in] Usage Conditions Operating Temperature Range -55 – 125 °C[-67 – 257 °F] Operation/Application Assembly Process Feature Pick and Place Cover	Housing Color	Natural
Connector Height 11 mm[.432 in] Row-to-Row Spacing 1.27 mm[.05 in] Stack Height 15 mm[.591 in] PCB Thickness (Recommended) 2.36 mm[.093 in] Jaage Conditions Operating Temperature Range -55 – 125 °C[-67 – 257 °F] Operation/Application Assembly Process Feature Pick and Place Cover	Housing Material	LCP (Liquid Crystal Polymer)
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Stack Height 15 mm[.591 in] PCB Thickness (Recommended) 2.36 mm[.093 in] Jage Conditions Operating Temperature Range -55 – 125 °C[-67 – 257 °F] Operation/Application Assembly Process Feature Pick and Place Cover	Connector Height	11 mm[.432 in]
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Usage Conditions Operating Temperature Range -55 – 125 °C[-67 – 257 °F] Operation/Application Assembly Process Feature Pick and Place Cover	Stack Height	15 mm[.591 in]
Operating Temperature Range -55 – 125 °C[-67 – 257 °F] Operation/Application Assembly Process Feature Pick and Place Cover	PCB Thickness (Recommended)	2.36 mm[.093 in]
Operation/Application Assembly Process Feature Pick and Place Cover	Jsage Conditions	
Assembly Process Feature Pick and Place Cover	Operating Temperature Range	-55 – 125 °C[-67 – 257 °F]
	Operation/Application	
Circuit Application Signal	Assembly Process Feature	Pick and Place Cover
	Circuit Application	Signal



Industry Standard	VITA 61
Packaging Features	
Packaging Quantity	230
Packaging Method	Tape & Reel
Other	
Comment	Conforms to requirement of VITA 61 (VITA 42 Alternate)., VITA 42 and VITA 61 are not intermateable but are footprint and XMC architecture compatible.

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JUL 2019 (201) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

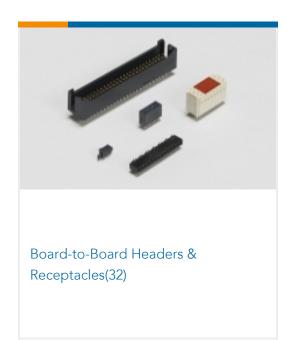
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Also in the Series | AMP Mezalok



Customers Also Bought























Documents

Product Drawings

Mezalok, Socket, 114 p, 15 mm, 30 Au, LF

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1-2102061-6_K.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1-2102061-6_K.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1-2102061-6_K.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

Mezalok Connector Brochure

English

SOSA Aligned Interconnect Solutions

English

Product Specifications

Product Specification

English